

Reflow Soldering Systems



Batch oven RP 6



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Our batch oven RP 6 is the newest model in the SEF reflow family. With its compact dimensions, a max. PCB size of 300x200 mm and its low power consumption it is capable of prototype production, small series production as well as component tests.

The heating chamber works with a mix of radiant heat by IR heaters and convection heat by radiators. Therewith max. reflow temperatures of 280°C-300°C on the PCB are possible. An inspection window in the hood allows to observe the soldering process.

The operation of the oven takes place by a PC or a notebook (not included in the delivery) which will be connected with the oven by a USB interface. The provided PC software offers at a glance all relevant information like oven status, explorer window for the selection of created profiles and a graphical display of the set temperature profiles.

The creation of the profiles takes place via a user-defined number of data points. For each data point you can adjust the temperature and the time so that a large number of profile variations are possible. Since it is possible to adjust the set profiles for the two IR heater fields (top front and rear) and the two radiators (sidewise left and right) separately, an adjustment of the square profile to different PCB assemblies is also possible.

The RP 6 has an integrated temperature profiler with 3 channels. The sockets for the connection are accessible at the front side of the oven. With the help of the provided thermocouple sensors the actual temperature profiles on the PCB can be measured and faded in the production window additionally. This allows an optimal comparison between set profiles and real profiles on the PCB. The optionally available Software "Mesy for Windows" allows the import of the actual profiles and a detailed analysis. With this software it is possible to detect values like max. positive and negative temperature increase, max. peak temperature, time above liquidus and so on.

After finishing the soldering process the drawer of the oven will open and two fans, integrated in the drawer and continuously adjustable, will cool down the PCBs to ambient temperature again.



System data

Dimensions:	750 x 650 x 440 mm DxWxH
Deepness (opened):	1000 mm
Weight:	approx. 50 kg
Min. PCB size:	10 x 10 mm
Max. PCB size:	200 x 300 mm
Colour:	RAL 7011/7047
Max. reflow temperature:	280 ° - 300 °C
PCB cooling:	2x ventilators, continuously adjustable
Noise level:	< 70dB (A)

PC system requirement

CPU:	Pentium IV or similar
RAM:	recommended 512 MB
Operating system:	Windows XP
Graphic board:	standard graphic board
Display:	min. 15", better 17" resolution min. 1024 x 768 dpi

Power supply

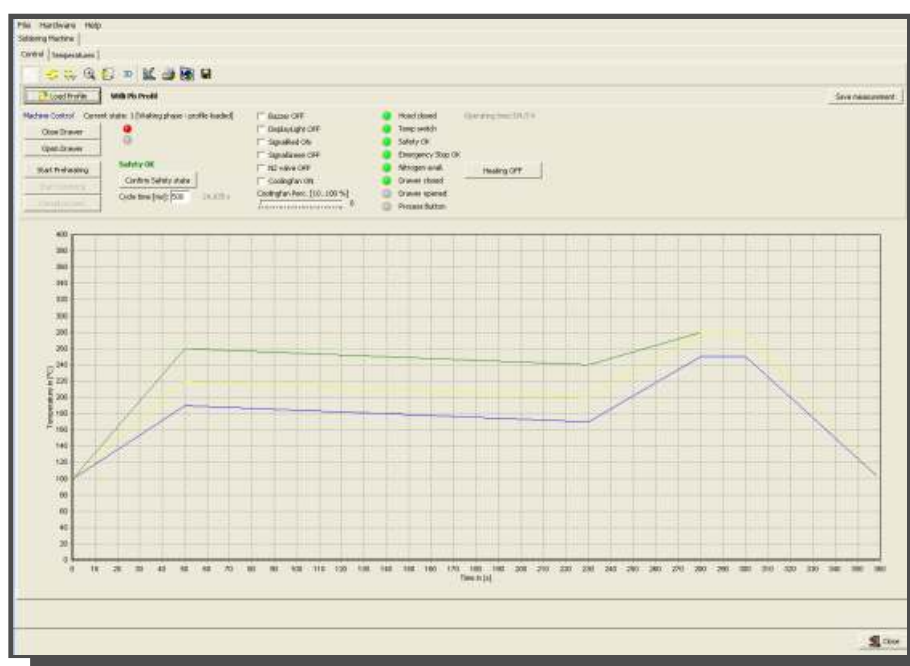
Voltage:	230 V /N/ PE
Nominal power consumption:	3,5 kW
Power consumption in steady-state: (at 100 °C)	0,5 kWh

Nitrogen supply (optional)

Faucet:	6 mm hose connection
Working pressure:	3 bar
Nitrogen consumption:	approx. 0,5 m³/h
Operating state (500 ppm):	approx. 1-2 min.
Best value after:	approx. 3 min (<50 ppm)

Exhaustion

Exhaust connector:	60 mm
Required exhaust volume:	40 m³/h (fan is already integrated)



RESY-Software
(picture similar)

SME - Surface Mount Equipment

MESY®-Profiler



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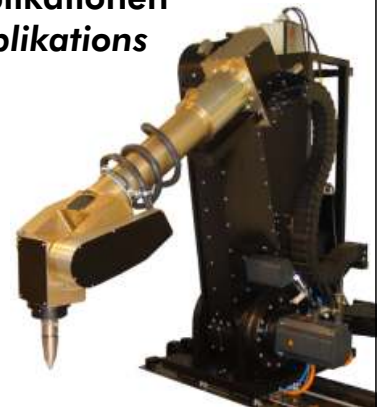
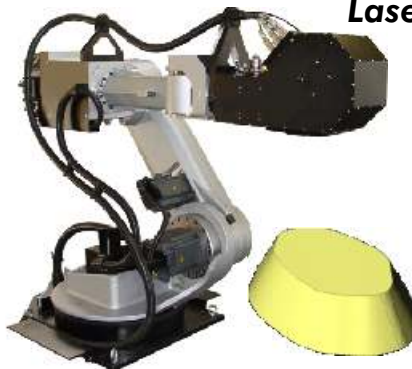
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